



## COMPANY INTRODUCTION

August 2025





## Enabling AI Semiconductor Device Packaging and Advanced Substrate Fabrication



**Business Transformation to Deliver Profitable Growth**



## Safe Harbor Statement



This Presentation may contain certain statements or information that constitute “forward-looking statements” (as such term is defined in Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended, and the Private Securities Litigation Reform Act of 1995). In some, but not all, cases, forward-looking statements can be identified by terminology such as “may,” “plan,” “anticipate,” “seek,” “will,” “expect,” “intend,” “estimate,” “anticipate,” “believe,” “continue,” “predict,” “potential,” “project,” “should,” “would,” “could,” “likely,” “future,” “target,” “forecast,” “goal,” “observe,” and “strategy” or the negative of these terms or other comparable terminology. Examples of forward-looking statements include statements regarding Amtech System, Inc.’s (“Amtech” or the “Company”) future financial results, operating results, business strategies, projected costs, products under development, competitive positions, plans and objectives of Amtech and its management for future operations, efforts to improve operational efficiencies and effectiveness and profitably grow our revenue, and enhancements to our technologies and expansion of our product portfolio. Such forward-looking statements and information are provided by the Company based on current expectations of the Company and reflect various assumptions of management concerning the future performance of the Company, and are subject to significant business, economic and competitive risks, uncertainties and contingencies, many of which are beyond the control of the Company. Accordingly, there can be no guarantee that such forward-looking statements or information will be realized. Actual results may differ materially from historical results and expectations based on forward-looking statements made in this document or elsewhere by Amtech or on its behalf. No representations or warranties are made as to the accuracy or reasonableness of any expectations or assumptions or the forward-looking statements or information based thereon. Each recipient of forward-looking statements should make an independent assessment of the merits of and should consult its own professional advisors. Except as required by law, we undertake no obligation to publicly update forward-looking statements, whether as a result of new information, future events, or otherwise. These forward-looking statements speak only as of the date of this Presentation. Except as required by any applicable law or regulation, the Company expressly disclaims any obligation or undertaking to release publicly any updates or revisions to any forward-looking statements contained herein to reflect any change in the Company’s expectations with regard thereto or any change in events, conditions or circumstances on which any such statement is based.



## Amtech Divisions

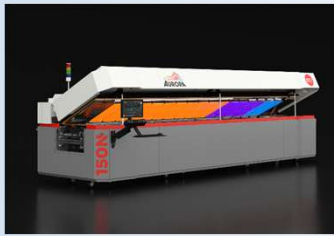
Capital equipment and consumables for semiconductor fabrication and packaging



### Thermal Processing Solutions (~70%)



AN AMTECH COMPANY



Reflow Oven



Belt Furnace

### Semiconductor Fabrication Solutions (~30%)



AN AMTECH COMPANY



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Lapping, Polishing, & Cleaning Consumables

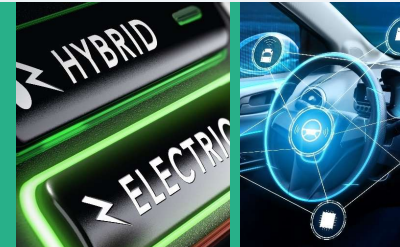
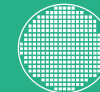


CMP Parts & Upgrades

Advanced packaging & electronics assembly equipment for applications such as AI GPUs, and advanced automotive electronics.



Consumables and equipment utilized in Silicon and Silicon Carbide semiconductor fabs for advanced automotive applications such as EV/HEV and industrial electronics.



Enabling production of AI enterprise servers and e-mobility systems



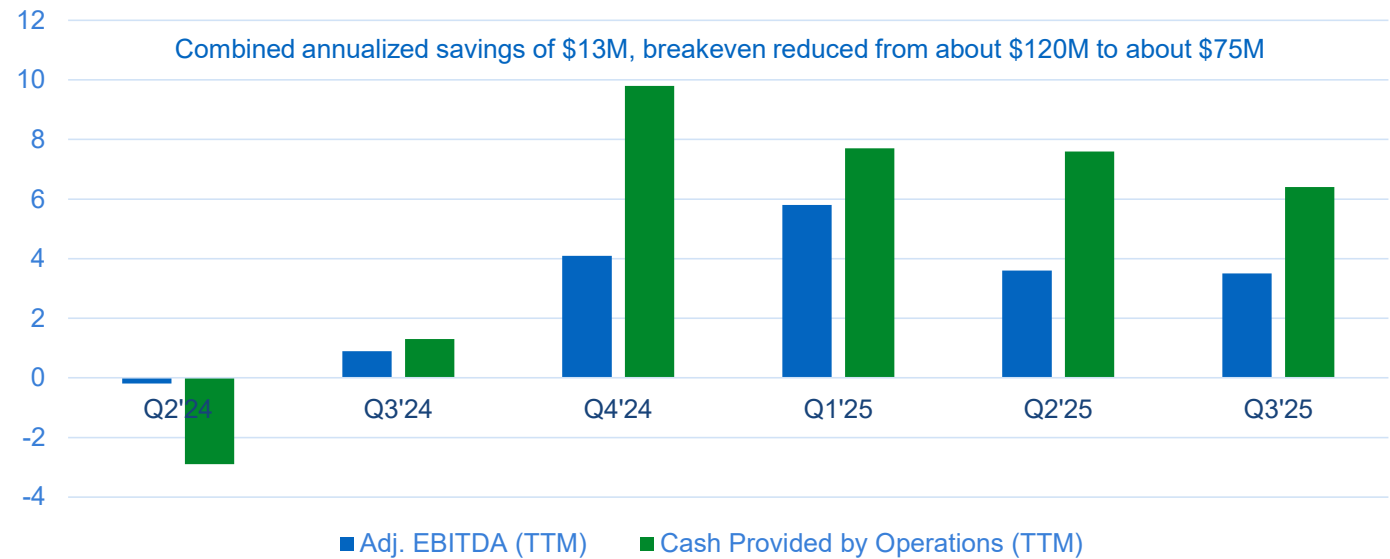
Approximate Revenue Contribution LTM, Dec 2024



## Optimized Operations Model Shows Positive Impact in Recent Quarters



### Cash Generation (M\$)



- Rationalized product-lines
- Migrated to semi-fabless model
- Right-sized organization

- Upgraded supply chain processes
- Improvements in value-based pricing
- Eliminated debt and built cash balance



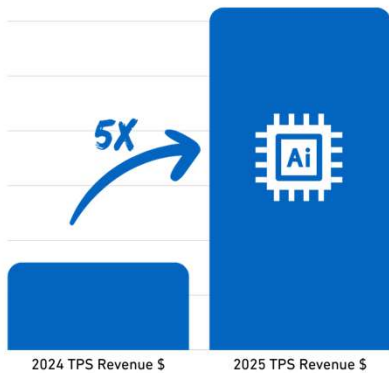


## AI Driving Revenue Growth in Thermal Processing Solutions Segment



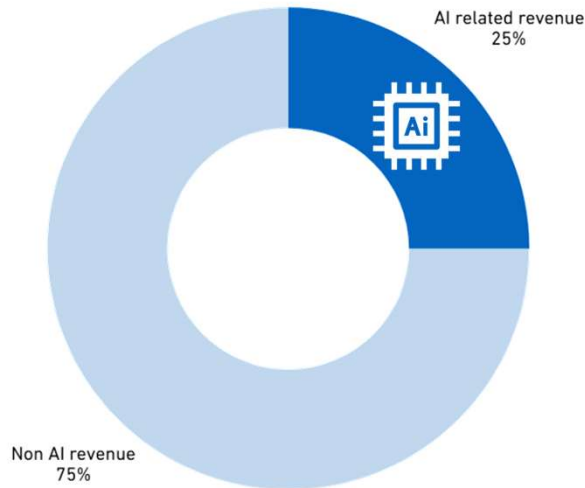
Year to Year Growth from AI Enablement

● AI Related \$

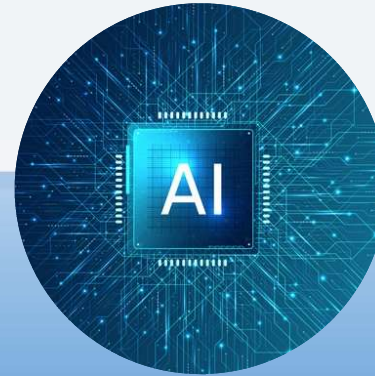


5X Growth in AI Annually  
60% Growth Sequentially

2025 Q2 TPS AI Related Revenue



25% of Segments Q3 Revenue

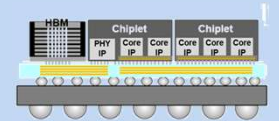


### Advanced Chip Packaging & Assembly



TrueFlat Thin Substrate Reflow Ovens  
Precision Convection Reflow Ovens

Flip chip packaging  
2.5D packaging  
CoWoS packaging  
Panel packaging  
Optical packaging  
Heavy board SMT



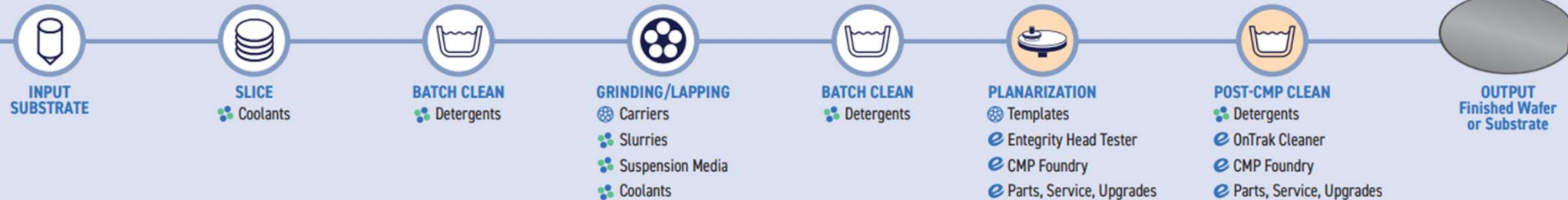
## Leveraging CMP Foundry Service to grow Chemical Consumables business



- CMP Foundry serves as a process development center for early-stage semiconductor and photonics companies.
- Enables rapid development and validation of CMP processes for advanced materials including Si, SiC, III-V, and photonic substrates.
- Specializes in planarity, uniformity, surface roughness, and CMP of patterned wafers.
- Supports process refinement and consumable screening to accelerate technology adoption and reduce development costs.
- Facilitates integration of Intersurface Dynamics' customized chemistries as process of record (POR) for cleaning and polishing.



### Semiconductor Substrate Manufacturing Process





INVESTMENT OPPORTUNITY

# Supplying Essential Semiconductor Equipment and Materials

**Increasing Cash Flow Generation and Creating Strong Operating Leverage to Deliver Profitable Growth Driven by AI Infrastructure and e-Mobility Markets**



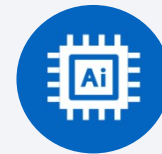
## **OPERATING LEVERAGE**

Committed to a disciplined approach to operations and scaled fixed costs



## **CASH FLOW GENERATION**

Funds from operations strategically invested in growth



## **HARNESS GROWTH MARKETS**

Market-leading products enabling scale in AI & e-mobility applications

